

SDIA3015 TYPE

●FEATURE

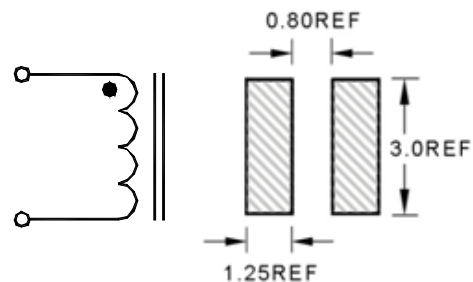
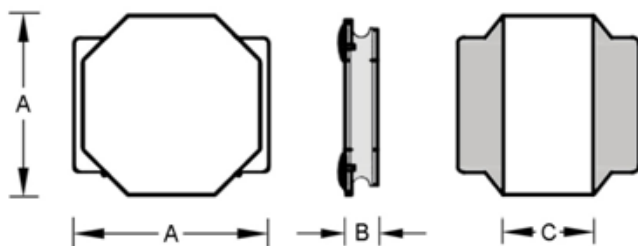
1. Low profile and small size (Height: 1.50mm Max)
2. Low DC resistance

●Applications

1. LCD panels
2. Digital camera , PDA and others

●Shape and Dimension

●Schematics and Land Patterns(mm)



A=3.00±0.20m/m ; B= 1.50m/m MAX ; C= 1.60m/m REF.

●Specification

Part Number	L(uH)	DCR(Ω Max)	Isat (mA)	Irms (mA)
SDIA3015-1R0N	1.0±30%	0.036	2100	2100
SDIA3015-1R5N	1.5±30%	0.048	1800	1820
SDIA3015-2R2M	2.2±20%	0.072	1500	1650
SDIA3015-3R3M	3.3±20%	0.096	1210	1230
SDIA3015-4R7M	4.7±20%	0.144	1100	1100
SDIA3015-6R8M	6.8±20%	0.192	870	880
SDIA3015-100M	10±20%	0.276	700	710
SDIA3015-150M	15±20%	0.432	560	560
SDIA3015-220M	22±20%	0.624	470	470
SDIA3015-330M	33±20%	1.008	390	370
SDIA3015-470M	47±20%	1.608	320	300

Note1. Measurement frequency of Inductance value : at 100KHz, 0.25V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25°C

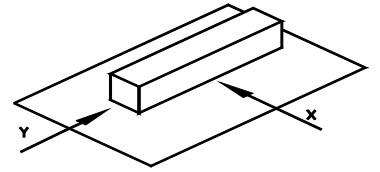
Note3. Isat : $\Delta L/L \leq 30\%$ (This indicates the value of current when the inductances is 30% lower than its initial value at D.C. superimposition)

Note4. Irms: D.C. current when at $\Delta t=40^\circ\text{C}$ (typ.). ($T_a=25^\circ\text{C}$)

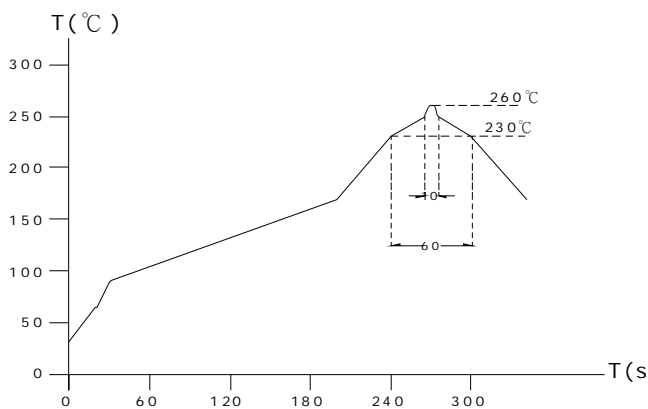
Note5. Packaging: Taping ; Quantity: 2000 Pieces/reel

GENERAL CHARACTERISTICS

1. Operating temperature range: -40 TO + 125°C (Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.
Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.
4. Insulating resistance: Over 100MΩ at 100V D.C. between coil and core.
5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
6. Temperature characteristics: Inductance coefficient $(0\sim 2,000)\times 10^{-6}/^{\circ}\text{C}$ (-25~+80°C degree Celsius), inductance deviation within $\pm 5.0\%$, after 96 hours.
7. Humidity characteristics (Moisture Resistance): Inductance deviation within $\pm 5\%$, after 96 hours in 90~95% relative humidity at $40 \pm 2^{\circ}\text{C}$ and 1 hour drying under normal condition.
8. Vibration resistance: Inductance deviation within $\pm 5\%$, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
9. Shock resistance: Inductance deviation within $\pm 5\%$, after being dropped once with 981m/s² (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
10. Resistance to Soldering Heat: 260°C, 10 seconds (See attached recommend reflow)
11. Storage condition: Temperature Range: 0°C ~ 35°C ; -40°C ~ 125°C (after PCB) , Humidity Range: 50% ~ 70% RH
12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
13. Reflow profile recommend:



Lead-free heat endurance test



Lead-free the recommended reflow condition

